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Intel® SSD 520 Series

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Intel® SSD 520 Series (120GB, 2.5in SATA 6Gb/s, 25nm, MLC)

Specifications

Essentials
Performance
Reliability
Package Specifications
Advanced Technologies

Compatible Products

Ordering / sSpecs /
Steppings

Specifications	
- Essentials	
Capacity	120 GB
Status	End of Life
Launch Date	Q1'12
Lithography Type	25 nm
Recommended Customer Price	N/A

- Performance	
Sequential Read (up to)	550 MB/s
Sequential Write (up to)	500 MB/s
Random Read (8GB Span) (up to)	25000 IOPS
Random Write (8GB Span) (up to)	40000 IOPS
Latency - Read	80 μs
Latency - Write	85 μs
Power - Active	850 mW (MobileMark 2007 Workload)
Power - Idle	600 mW (DIPM)

2.17 G _{RMS} (5-700 Hz)
3.13 G _{RMS} (5-800 Hz)
1,500 G/.5 msec
0°C to 70°C
1,200,000 Hours
1 sector per 10 ¹⁶
5 yrs

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Components	Intel NAND Flash Memory Multi- Level Cell (MLC) Technology	
Weight	Up to 78 grams	
Form Factor	2.5" 7mm	
Interface	SATA 3.0 6Gb/S	
- Advanced Technologies		
Enhanced Power Loss Data Protection	No	
Hardware Encryption	AES 128 bit	

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 $\label{lem:conditions} \mbox{Refer to Datasheet for formal definitions of product properties and features.}$

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Package Specifications

Downloaded from Arrow.com.

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